The device from WO2015/161868A1 can also be operated in a vacuum, wherein the entire device must be evacuated. The embossing stamp is not a flexible, soft film stamp stretched across a film frame, but rather a hard polymer stamp.

Embodiments of the invention eliminate at least partially, in particular completely eliminate, the drawbacks listed in the prior art. In particular, embodiments of the invention disclose an improved method and an improved device for the processing, in particular embossing of substrates.

All combinations of at least two features indicated in the description, in the claims and/or the drawings fall within the scope of the invention. In the case of stated value ranges, values also lying within the stated limits should be deemed to be disclosed as limiting values and can be claimed in any combination.

According to a first aspect of the invention, there is provided a method for the processing, in particular the nano-embossing, of a substrate with at least the following steps: a) provision of a substrate mounting arrangement for mounting the substrate, b) provision of a device for processing the substrate, c) formation of a local and fluidically tight processing space between the substrate mounting arrangement and the device, d) evacuation of the processing space and e) processing of the substrate, wherein the evacuation in step d) takes place after the formation of the processing space in step c), wherein the device includes a flexible film stamp for the processing, in particular for the embossing, of the substrate and in step e) a fluidically tight flushing space between the device and the film stamp is flushed for curving the film stamp, wherein the processing space and the flushing space are separated from one another fluidically by the film stamp.

According to a second aspect of the invention, there is provided a device for processing a substrate, at least including: i) a substrate mounting arrangement for the mounting of the substrate, ii) a device for processing the substrate, iii) means for the formation of a local and fluidically tight processing space between the substrate mounting arrangement and the device vi) evacuation means for evacuating the processing space v) processing means for processing the substrate, wherein the processing means include a flexible film stamp for the embossing, in particular the nano-embossing, of the substrate, wherein the device additionally include flushing means for the formation of a fluidically tight flushing space between the device and the film stamp, wherein the flushing space is separated fluidically by the film stamp from the processing space, and wherein the film stamp is deformed by the flushing means in a targeted manner.